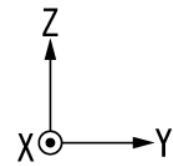




Figure 1 is a perspective view of a multi-layered circuit board assembly 30. The assembly includes a top layer 35, a middle layer 40, and a bottom layer 33 (21). It features multiple layers of conductive traces 45 and 50, and various components 60. Section lines III-III and I-I are indicated.



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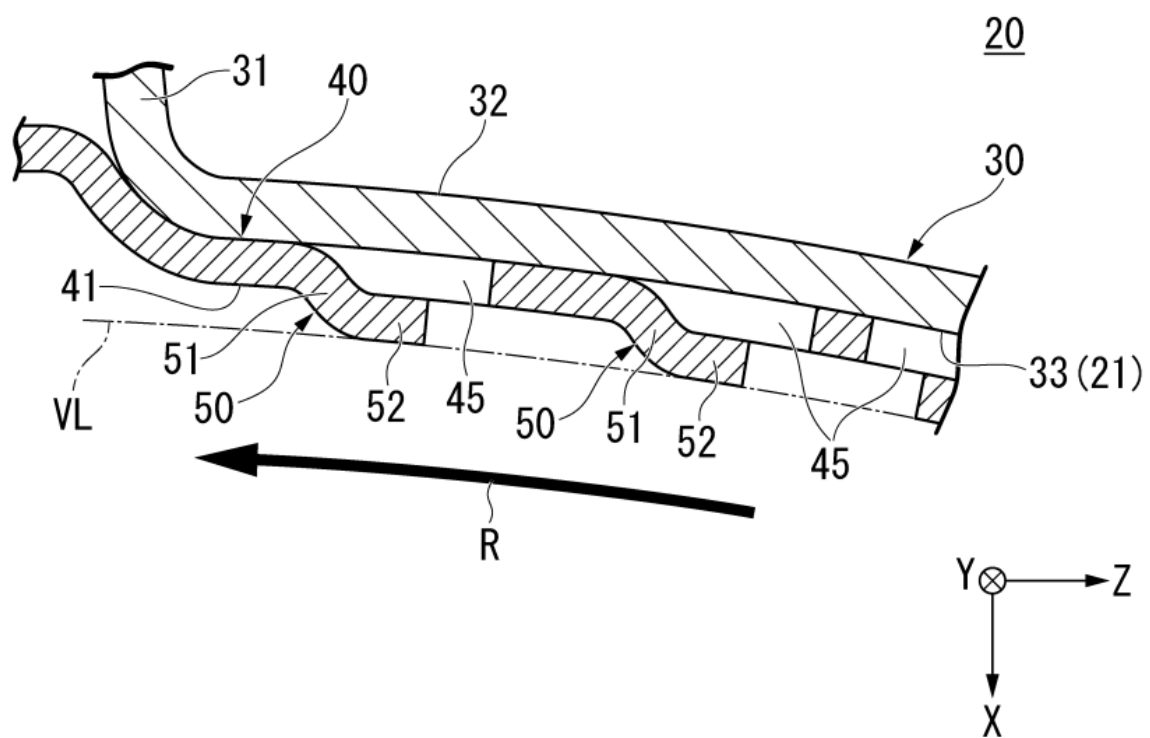


FIG. 3



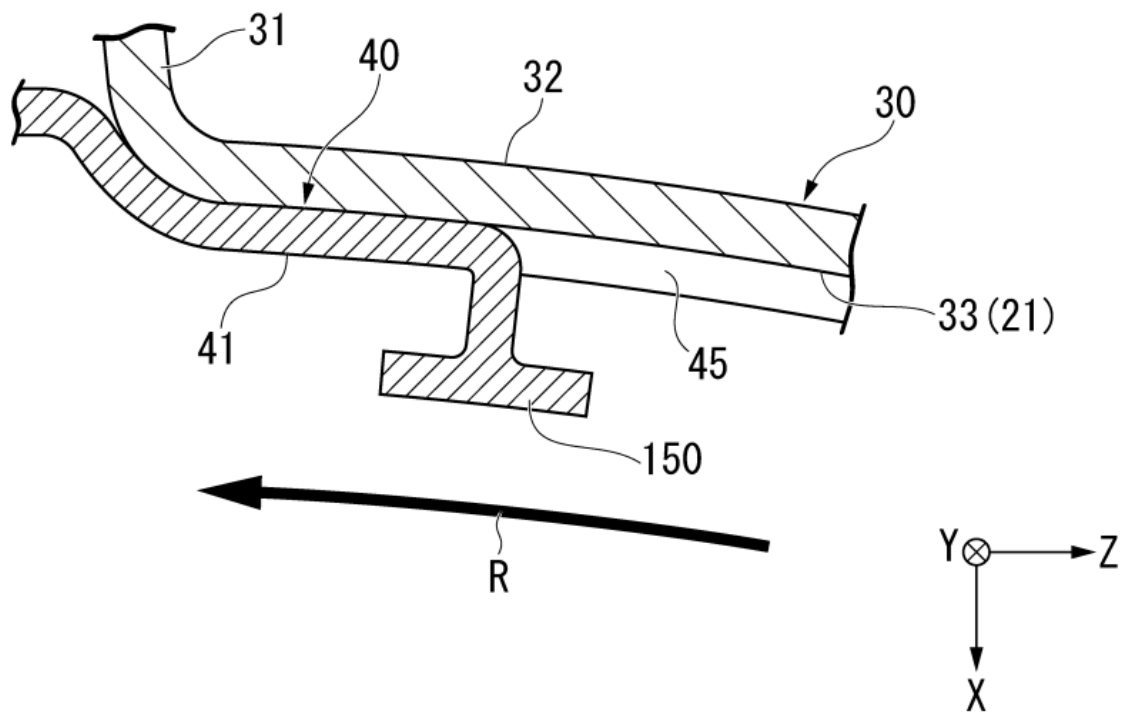


FIG. 5

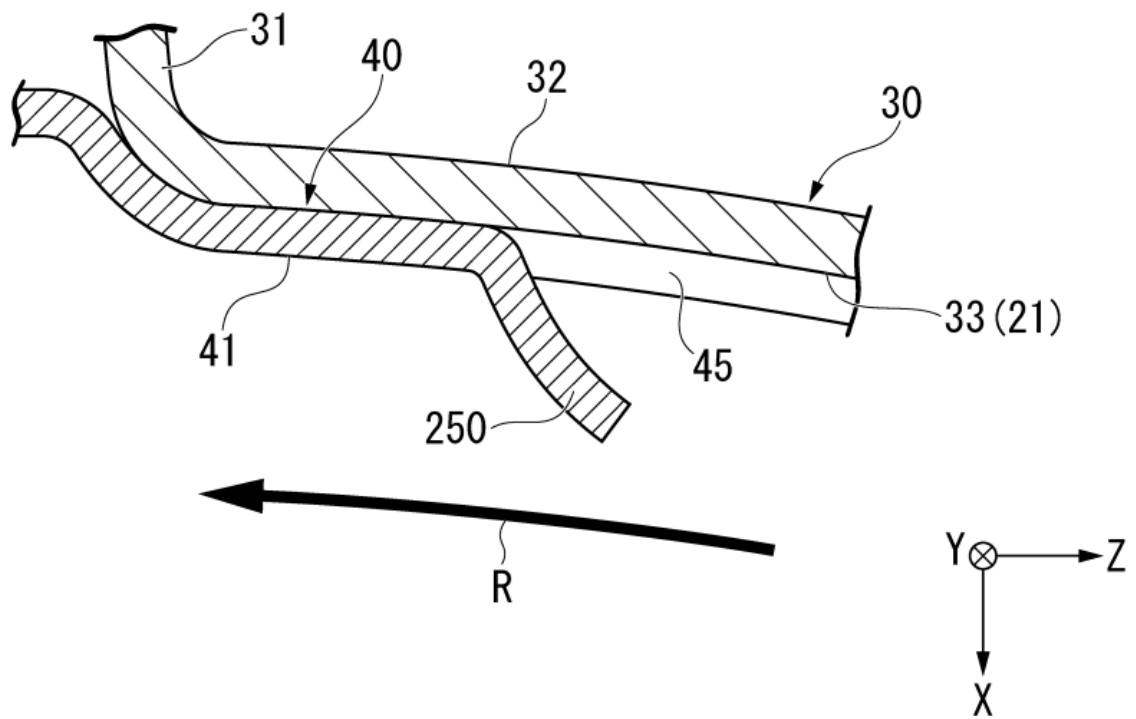


FIG. 6